



**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10V, I_D=15A$	-	28	37	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	-	36	42	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$	-	817	-	pF
$C_{oss}$	Output Capacitance		-	49	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	41	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30V, I_D=4.5A,$ $V_{GS}=10V$	-	14	-	nC
$Q_{gs}$	Gate-Source Charge		-	2.9	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	5.2	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30V, I_D=2A,$ $R_L=6.7\Omega, R_G=3\Omega,$ $V_{GS}=10V$	-	5	-	ns
$t_r$	Turn-on Rise Time		-	2.6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	16.1	-	ns
$t_f$	Turn-off Fall Time		-	2.3	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	74	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=15A$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}, I_F=15A,$ $di/dt=100A/\mu s$	-	35	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	53	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=6.1A$ 3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

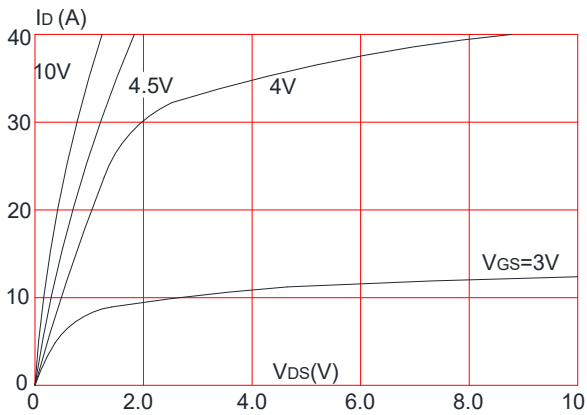


Figure 2: Typical Transfer Characteristics

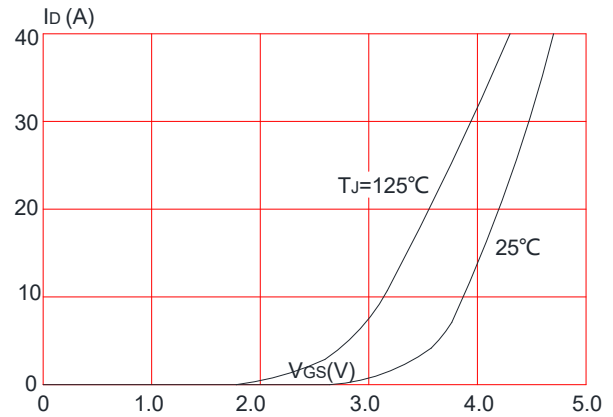


Figure 3: On-resistance vs. Drain Current

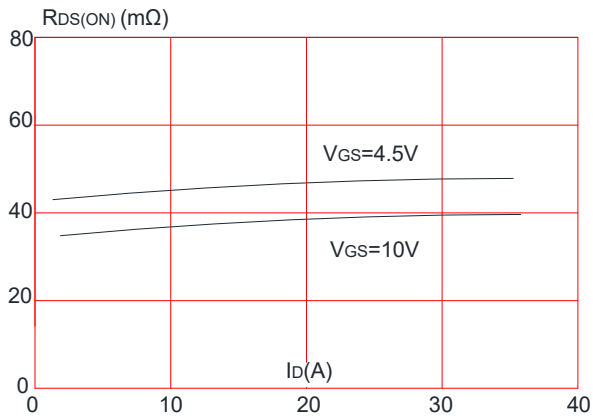


Figure 4: Body Diode Characteristics

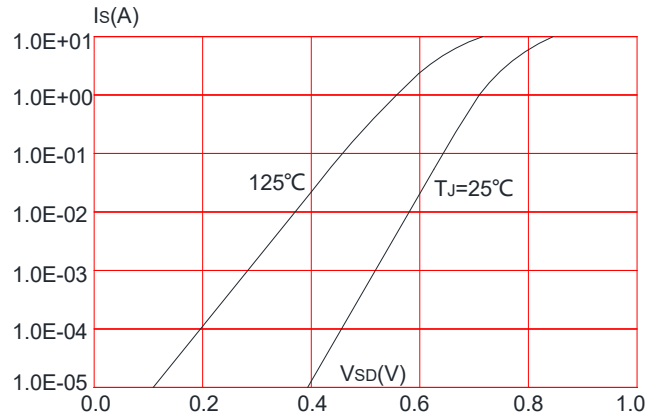


Figure 5: Gate Charge Characteristics

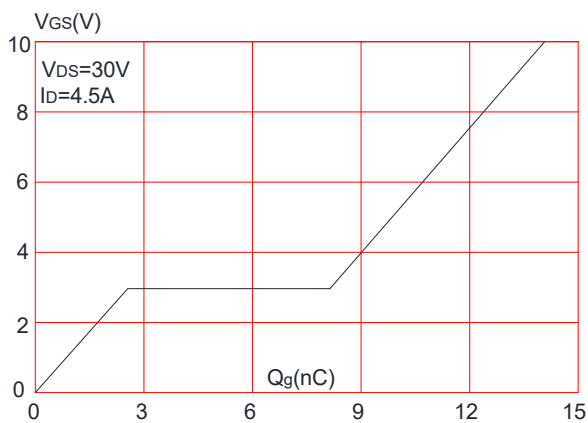
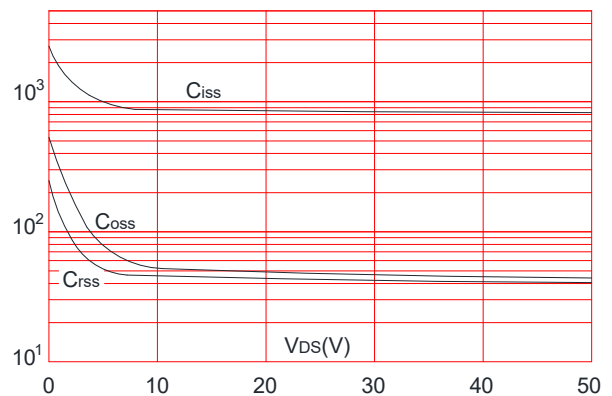
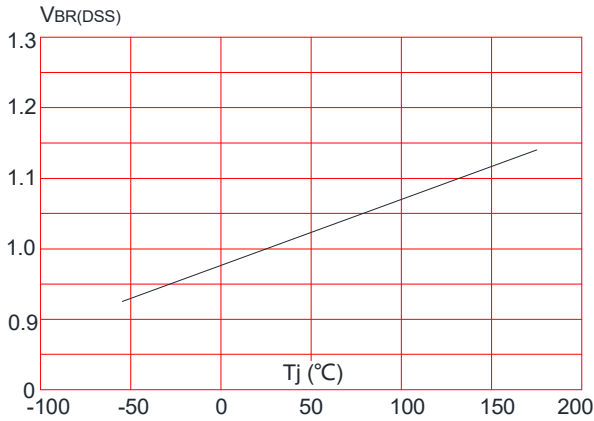


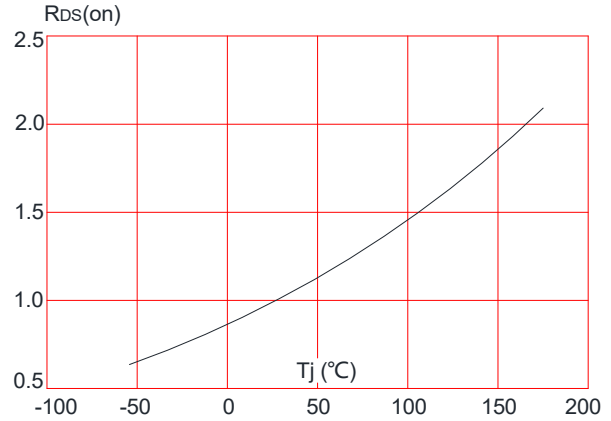
Figure 6: Capacitance Characteristics



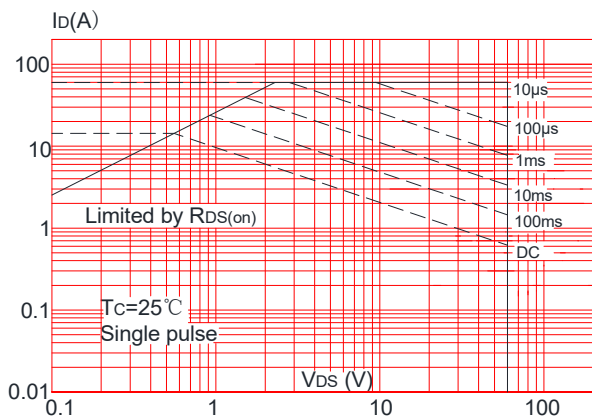
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



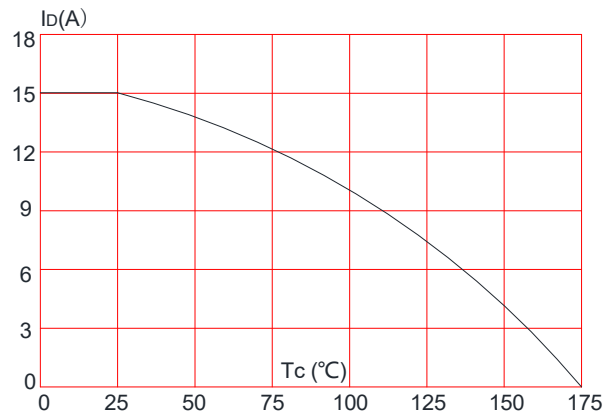
**Figure 8:** Normalized on Resistance vs. Junction Temperature



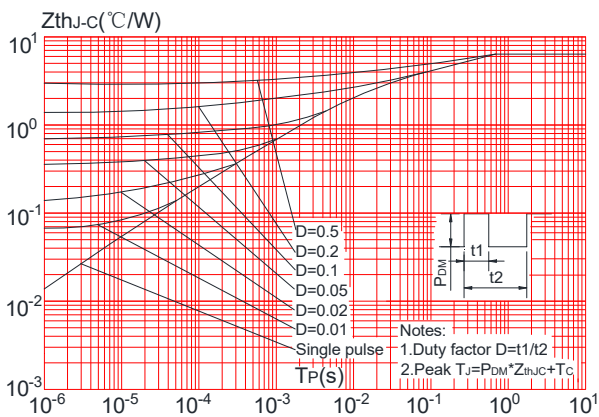
**Figure 9:** Maximum Safe Operating Area



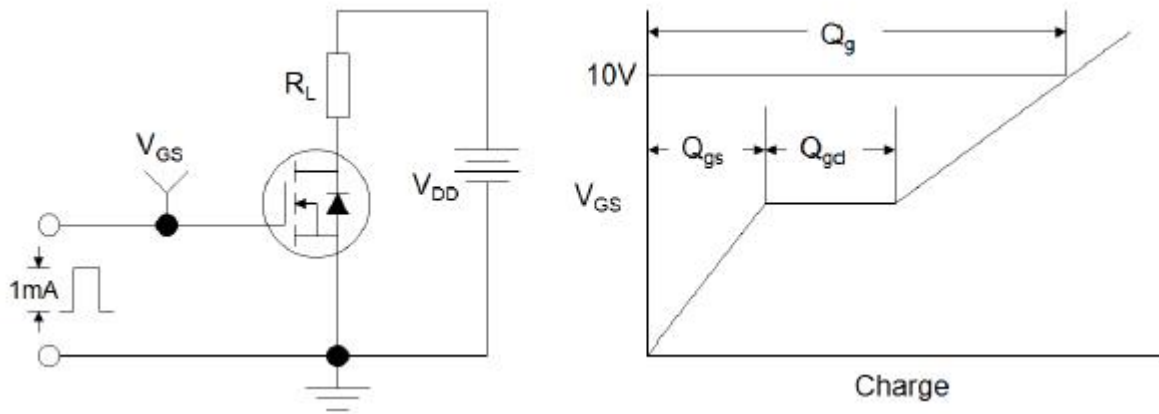
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



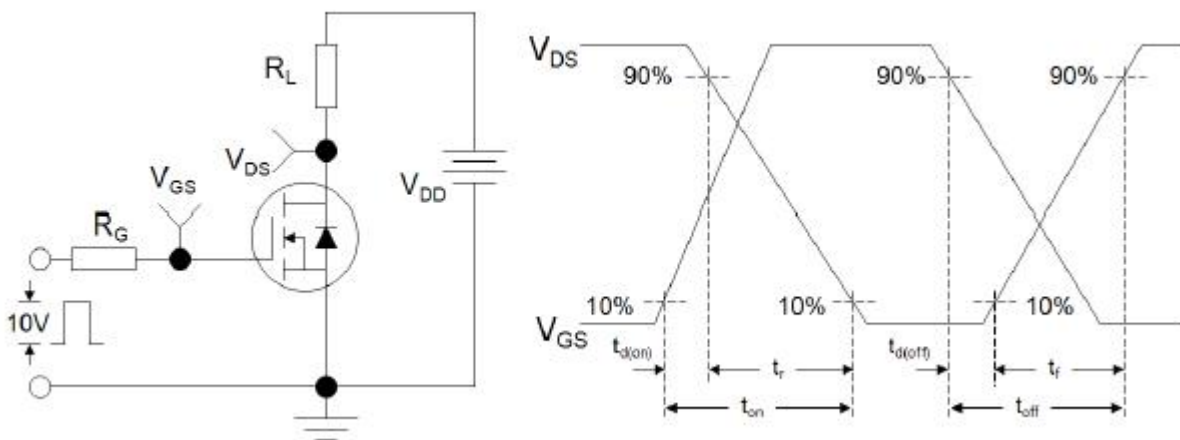
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



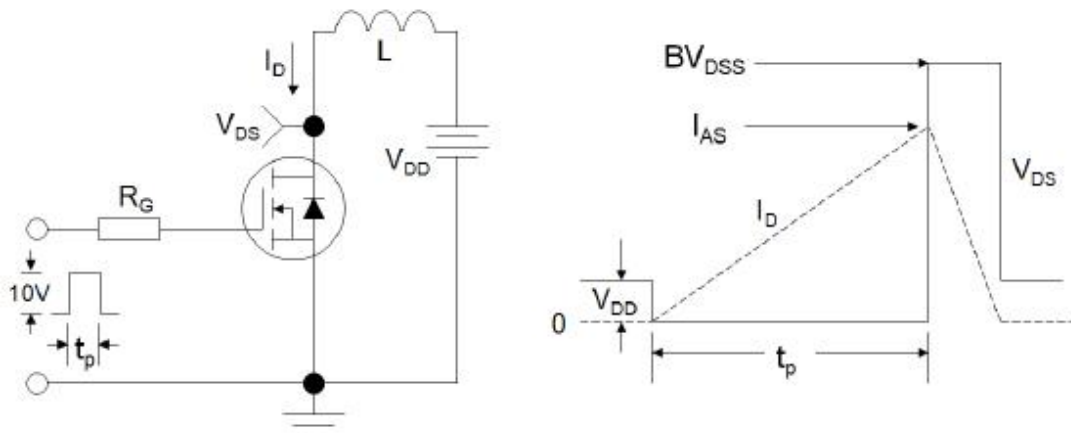
**Test Circuit**



**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveforms**



**Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms**

Package Information:TO-252-3L

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
-	1.100	1.300	0.043	0.051
	e	e	e	e
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	